

N-Channel 30-V (D-S) MOSFET

| PRODUCT SUMMARY | | | | | | |
|---------------------|----------------------------------|---------------------------------|-----------------------|--|--|--|
| V _{DS} (V) | $R_{DS(on)}$ (Ω) | I _D (A) ^a | Q _g (Typ.) | | | |
| 30 | 0.006 at V _{GS} = 10 V | 24 | 12 nC | | | |
| 30 | 0.008 at V _{GS} = 4.5 V | 21 | 12110 | | | |

FEATURES

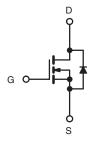
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET[®] Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested
- Compliant to RoHS Directive 2002/95/EC



ROHS COMPLIANT HALOGEN FREE

APPLICATIONS

- DC/DC Converter
 - Notebook Vcore
 - POL



N-Channel MOSFET

| | | SO-8 | | |
|-------------------|-------|----------|------------------|-------------|
| s [s [g [| 2 3 4 | | 8 7 6 5 | D D D |
| | | Top View | | |

Ordering Information: Si4156DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

| Parameter | | Symbol | Limit | Unit | |
|--|--|-----------------------------------|--------------------------|------|--|
| Drain-Source Voltage | | V _{DS} | 30 | V | |
| Gate-Source Voltage | | V _{GS} | ± 20 | v | |
| | T _C = 25 °C T _C = 70 °C | | 24 19 | | |
| Continuous Drain Current (T _J = 150 °C) | T _A = 25 °C | I _D | 15.7 ^{b, c} | Α . | |
| $T_A = 70$ | | | 12.5 ^{b, c} | | |
| Pulsed Drain Current Avalanche Current | | I _{DM} | 70 35 | | |
| Avalanche Energy | L = 0.1 mH | I _{AS} | 61 | mJ | |
| Continuous Source-Drain Diode Current $T_C = 25 ^{\circ}\text{C}$ $T_A = 25 ^{\circ}\text{C}$ | | I _S | 5 2.1 ^{b, c} | Α | |
| | T _C = 25 °C T _C = 70 °C | _ | 6 3.8 | | |
| Maximum Power Dissipation | T _A = 25 °C T _Δ = 70 °C | P _D | 2.5 ^{b, c} | W | |
| Operating Junction and Storage Temperature Range | | T _J , T _{stg} | - 55 to 150 | -°C | |
| Soldering Recommendations (Peak Tempera | | 260 | | | |

| THERMAL RESISTANCE RATINGS | | | | | | | |
|---|--------------|-------------------|---------|---------|------|--|--|
| Parameter | | Symbol | Typical | Maximum | Unit | | |
| Maximum Junction-to-Ambient ^{b, d} | t ≤ 10 s | R _{thJA} | 37 | 50 | °C/W | | |
| Maximum Junction-to-Foot (Drain) | Steady State | $R_{th,IF}$ | 17 | 21 | 0/11 | | |

Notes:

- a. Based on $T_C = 25$ °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 10 s.
- d. Maximum under Steady State conditions is 81 °C/W.



| Parameter | Symbol | Test Conditions | Min. | Тур. | Max. | Unit |
|---|-------------------------|--|------|--------|-------|-------|
| Static | | | | | | |
| Drain-Source Breakdown Voltage | V _{DS} | $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$ | 30 | | | V |
| V _{DS} Temperature Coefficient | $\Delta V_{DS}/T_{J}$ | I _D = 250 μA | | 24 | | mV/°C |
| V _{GS(th)} Temperature Coefficient | $\Delta V_{GS(th)}/T_J$ | Ι _D = 250 μΑ | | - 6 | | |
| Gate-Source Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}$, $I_D = 250 \mu A$ | 1.15 | | 2.2 | ٧ |
| Gate-Source Leakage | I _{GSS} | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$ | | | ± 100 | nA |
| Zawa Oata Walkawa Busin Oawant | | V _{DS} = 30 V, V _{GS} = 0 V | | | 1 | μΑ |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} = 30 V, V _{GS} = 0 V, T _J = 55 °C | | | 5 | |
| On-State Drain Current ^a | I _{D(on)} | $V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$ | 50 | | | Α |
| | Б | V _{GS} = 10 V, I _D = 15.7 A | | 0.0048 | 0.006 | Ω |
| Drain-Source On-State Resistance ^a | R _{DS(on)} | V _{GS} = 4.5 V, I _D = 13.2 A | | 0.0064 | 0.008 | |
| Forward Transconductance ^a | 9 _{fs} | V _{DS} = 15 V, I _D = 15.7 A | | 82 | | S |
| Dynamic ^b | 1 | | | | | _ |
| Input Capacitance | C _{iss} | | | 1700 | | |
| Output Capacitance | C _{oss} | $V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$ | | 350 | | pF |
| Reverse Transfer Capacitance | C _{rss} | | | 140 | | |
| Total Cata Charge | Qg | $V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 19 \text{ A}$ | | 28 | 42 | nC |
| Total Gate Charge | | | | 12 | 21 | |
| Gate-Source Charge | Q_{gs} | $V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 19 \text{ A}$ | | 5.4 | | |
| Gate-Drain Charge | Q _{gd} | | | 4.6 | | |
| Gate Resistance | R_g | f = 1 MHz | 0.2 | 1.2 | 2.4 | Ω |
| Turn-On Delay Time | t _{d(on)} | | | 25 | 40 | |
| Rise Time | t _r | $V_{DD} = 15 \text{ V}, R_{L} = 1.5 \Omega$ | | 20 | 30 | |
| Turn-Off Delay Time | t _{d(off)} | $I_D \cong 10 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$ | | 25 | 40 | |
| Fall Time | t _f | | | 15 | 25 | |
| Turn-On Delay Time | t _{d(on)} | | | 12 | 20 | ns |
| Rise Time | t _r | V_{DD} = 15 V, R_{L} = 1.5 Ω | | 10 | 15 | |
| Turn-Off Delay Time | t _{d(off)} | $I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$ | | 25 | 40 | |
| Fall Time | t _f | | | 10 | 15 | |
| Drain-Source Body Diode Characteristi | cs | | | | | |
| Continuous Source-Drain Diode Current | I _S | T _C = 25 °C | | | 30 | ^ |
| Pulse Diode Forward Current | I _{SM} | | | | 70 | Α |
| Body Diode Voltage | V_{SD} | I _S = 10 A, V _{GS} = 0 V | | 0.8 | 1.2 | V |
| Body Diode Reverse Recovery Time | t _{rr} | | | 25 | 50 | ns |
| Body Diode Reverse Recovery Charge | Q _{rr} | L = 10 A dl/dt = 100 A/vo T = 05 °C | | 17 | 35 | nC |
| Reverse Recovery Fall Time | t _a | $I_F = 10 \text{ A, dI/dt} = 100 \text{ A/}\mu\text{s, T}_J = 25 ^{\circ}\text{C}$ | | 13 | | |
| Reverse Recovery Rise Time | t _b | | | 12 | | ns |

Notes:

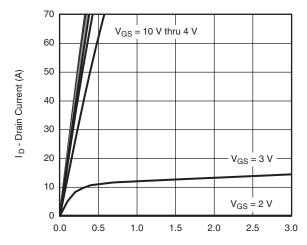
- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



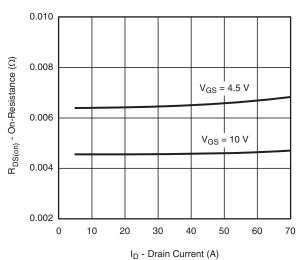


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

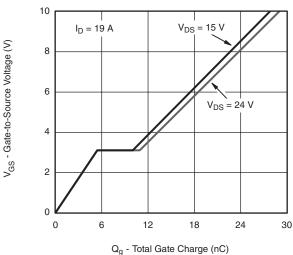


V_{DS} - Drain-to-Source Voltage (V)

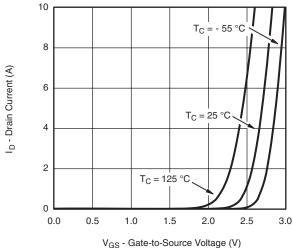
Output Characteristics



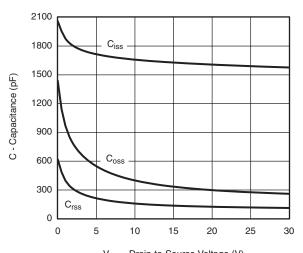
On-Resistance vs. Drain Current and Gate Voltage



Gate Charge

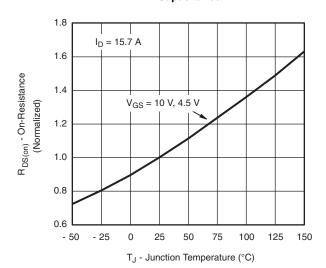


Transfer Characteristics



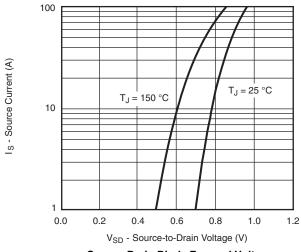
V_{DS} - Drain-to-Source Voltage (V)

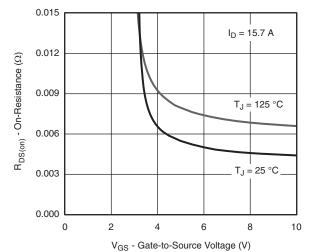
Capacitance



On-Resistance vs. Junction Temperature

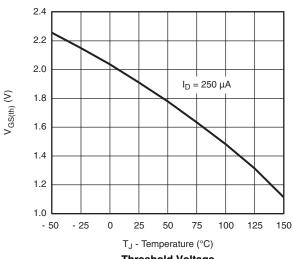
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

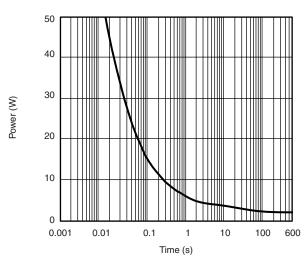




Source-Drain Diode Forward Voltage

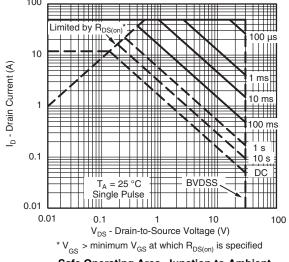






Threshold Voltage

Single Pulse Power (Junction-to-Ambient)

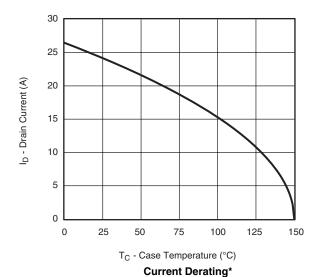


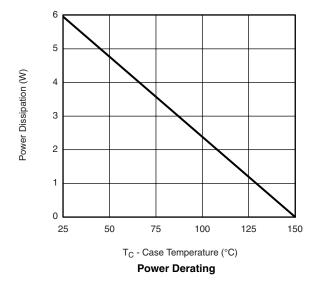




Si4156DY Vishay Siliconix

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

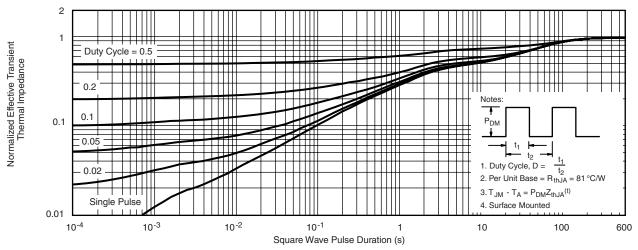




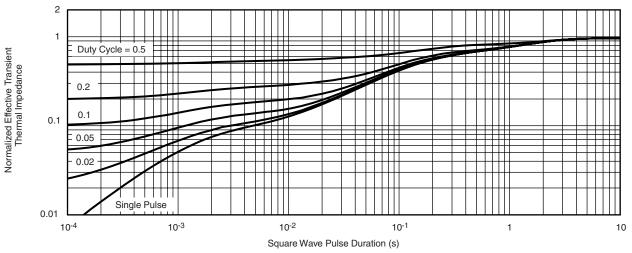
 $^{^*}$ The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppq?64822.



SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







| | MILLIM | MILLIMETERS INCHES | | | | |
|--------------------------------|--------|--------------------|-----------|-------|--|--|
| DIM | Min | Max | Min | Max | | |
| Α | 1.35 | 1.75 | 0.053 | 0.069 | | |
| A ₁ | 0.10 | 0.20 | 0.004 | 0.008 | | |
| В | 0.35 | 0.51 | 0.014 | 0.020 | | |
| С | 0.19 | 0.25 | 0.0075 | 0.010 | | |
| D | 4.80 | 5.00 | 0.189 | 0.196 | | |
| Е | 3.80 | 4.00 | 0.150 | 0.157 | | |
| е | 1.27 | BSC | 0.050 BSC | | | |
| Н | 5.80 | 6.20 | 0.228 | 0.244 | | |
| h | 0.25 | 0.50 | 0.010 | 0.020 | | |
| L | 0.50 | 0.93 | 0.020 | 0.037 | | |
| q | 0° | 8° | 0° | 8° | | |
| S | 0.44 | 0.64 | 0.018 | 0.026 | | |
| ECN: C-06527-Rev. I. 11-Sep-06 | | | | | | |

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RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

Return to Index

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